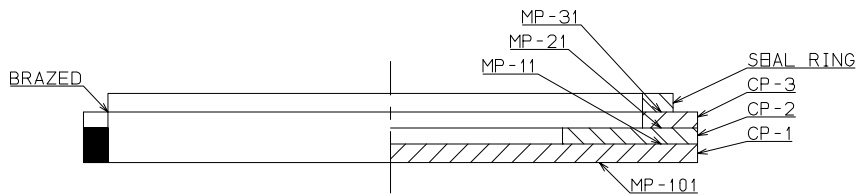


NOTES:

1. GENERAL TOLBRANCE : ±1% N.L.T. ±0.13.
2. ELBECTRIC Ni PLATING : 1.27~8.89 MICRON.(SOLDBR PAD)
ELBECTRIC Au PLATING : 1.00 MICRON MIN.(SOLDBR PAD)
3. * MARK TO BE MATERIAL DIMENSION.
4. CONNECTION : (A-4),(B-1),(2-3-S/R)
5. ■ PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
6. SEALING METHOD OF THIS PRODUCT SHALL BE SBAM WELD.



TOLERANCE	REVISION	SBB ATTACHED EXCEPTIONS SHEET.				TITLE	
±1% N.L.T.±0.13	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	5X3.2 CRYSTAL	
ANGLES	25 : 1	mm	3rd			PART NO.	REV.
						S5032XTAL2	0
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	DWG NO.	SHT/OF
90%MIN.A1203 (NA-31B BLACK)	Shigetomi	Yamahata	Ohba	Kumura	Sugi		1/5
	Nov.05.02	Nov.05.02	Nov.05.02	Nov.05.02	Nov.05.02		